



TE Internal #: 8-2355632-1
 DIMM Sockets, Double Data Rate (DDR) 5, Board-to-Component,
 288 Position, Surface Mount Mount, Vertical Module Orientation

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 5**
 Connector System: **Board-to-Component**
 Number of Positions: **288**
 PCB Mounting Style: **Surface Mount**
 Module Orientation: **Vertical**

Features

Product Type Features

| | |
|-----------------------------------|--------------------------|
| DRAM Type | Double Data Rate (DDR) 5 |
| Connector System | Board-to-Component |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|---------------------|----------|
| Number of Bays | 2 |
| Number of Keys | 1 |
| Number of Rows | 2 |
| Number of Positions | 288 |
| Module Orientation | Vertical |

Electrical Characteristics

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|--------------|-------|
| DRAM Voltage | 1.1 V |
|--------------|-------|

Body Features

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|--------------------------------|--------------------------------|
| PCB Retention Feature Material | Stainless Steel |
| Ejector Material Color | Natural |
| Ejector Material | High Temperature Thermoplastic |



| | |
|-------------------|------------------------|
| Latch Color | Natural |
| Ejector Location | Both Ends |
| Latch Material | High Temperature Nylon |
| Module Key Type | DRAM |
| Connector Profile | Standard |
| Ejector Type | Rotary |

Contact Features

| | |
|---|--|
| Memory Socket Type | Memory Card |
| Socket Style | DIMM |
| PCB Contact Termination Area Plating Material Thickness | 3 μm [120 μin] |
| Contact Mating Area Plating Material Thickness | .76 μm [30 μin] |
| Contact Mating Area Plating Material | Gold |
| Contact Underplating Material | Tin |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Copper Alloy |
| Contact Current Rating (Max) | 1.5 A |

Termination Features

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|--------------------------------|-----------------|
| Insertion Style | Direct Insert |
| Termination Post & Tail Length | .89 mm[.035 in] |

Mechanical Attachment

| | |
|--------------------------|---------------|
| Mount Angle | Vertical |
| PCB Mount Alignment Type | None |
| Mating Alignment Type | 1 Key |
| Mating Alignment | With |
| PCB Mount Retention | With |
| PCB Mount Retention Type | Tab |
| PCB Mounting Style | Surface Mount |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|------------------------|
| Housing Material | High Temperature Nylon |
| Housing Color | Natural |
| Centerline (Pitch) | .85 mm[.033 in] |



Dimensions

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|-------------------------|------------------|
| Profile Height from PCB | 21.3 mm[.083 in] |
| Row-to-Row Spacing | 3 mm[.118 in] |

Usage Conditions

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|-----------------------------|----------------------------|
| Operating Temperature Range | -55 – 105 °C[-67 – 221 °F] |
|-----------------------------|----------------------------|

Operation/Application

| | |
|---------------------|-----------------|
| Circuit Application | High Speed Data |
|---------------------|-----------------|

Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features

| | |
|--------------------|------------|
| Packaging Quantity | 640 |
| Packaging Method | Box & Tray |

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Not reviewed for solder process capability |

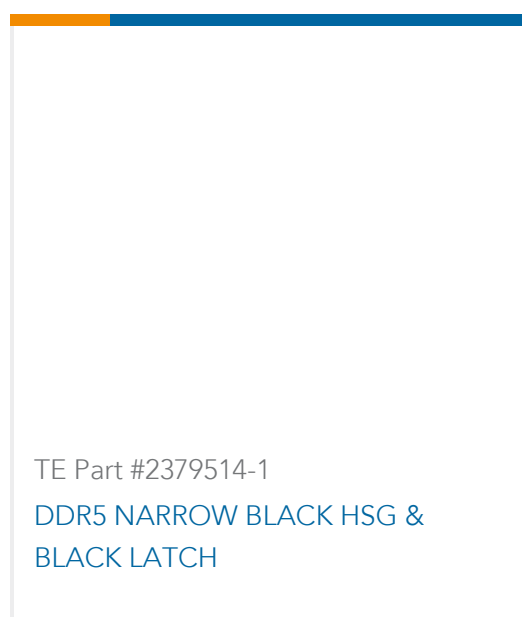
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought



Documents

Product Drawings

DDR5 DIMM NATURAL HSG AND NATURAL LATCH

English

CAD Files

Customer View Model



[ENG_CVM_CVM_8-2355632-1_A.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_8-2355632-1_A.3d_stp.zip](#)

English

Customer View Model

[ENG_CVM_CVM_8-2355632-1_A.3d_igs.zip](#)

English

3D PDF

3D

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Product Specifications

[Application Specification](#)

English

Product Environmental Compliance

[Product Compliance](#)

English

[Product Compliance](#)

English